

Notice of References Cited	Application/Control No. 10/735,531	Applicant(s)/Patent Under Reexamination COLE ET AL.	
	Examiner Matt P. Hodges	Art Unit 2879	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-3,732,452	05-1973	Axmark et al.	313/538
	B	US-			
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	F	US-			
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	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Cheng et al., Localized Silicon Fusion and Eutectic Bonding for MEMS Fabrication and Packaging, Journal of Microelectromechanical systems, VOL. 9, No. 1, March 2000, pages 3-7
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.